

Conductive copper pastes for PV metallization

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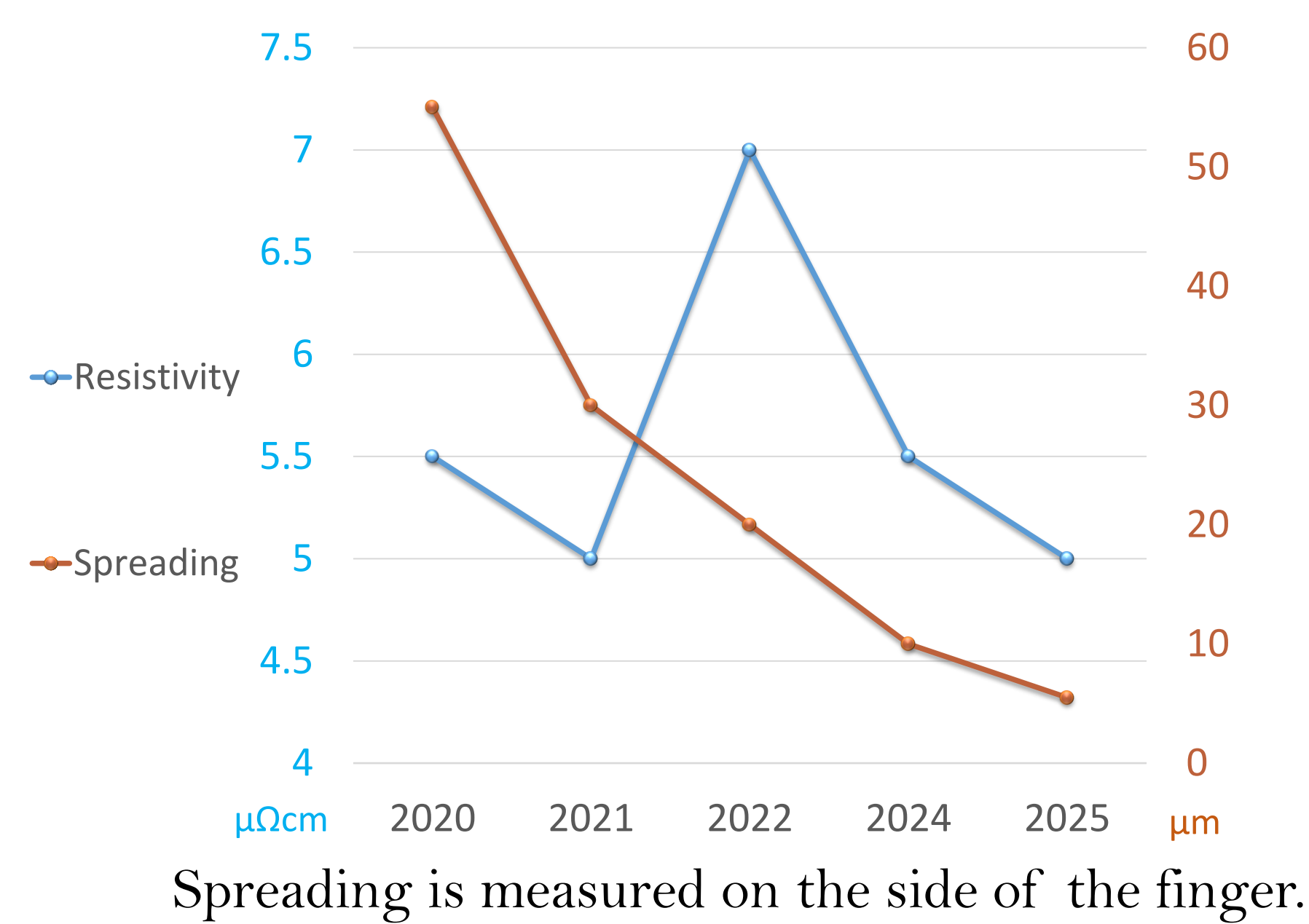
Introduction and Motivation

The silver demand by the PV industry is exceeding 16% of total global demand and is expected to continue growing alongside the increasing demand for solar panels. Therefore, there is a large motivation to replace, at least part of the silver usage by other more abundant metals.

Copprint's highly conductive copper pastes present an excellent alternative. The printing process is identical to the current screen-printing method, and the paste price is significantly lower than the standard silver pastes.

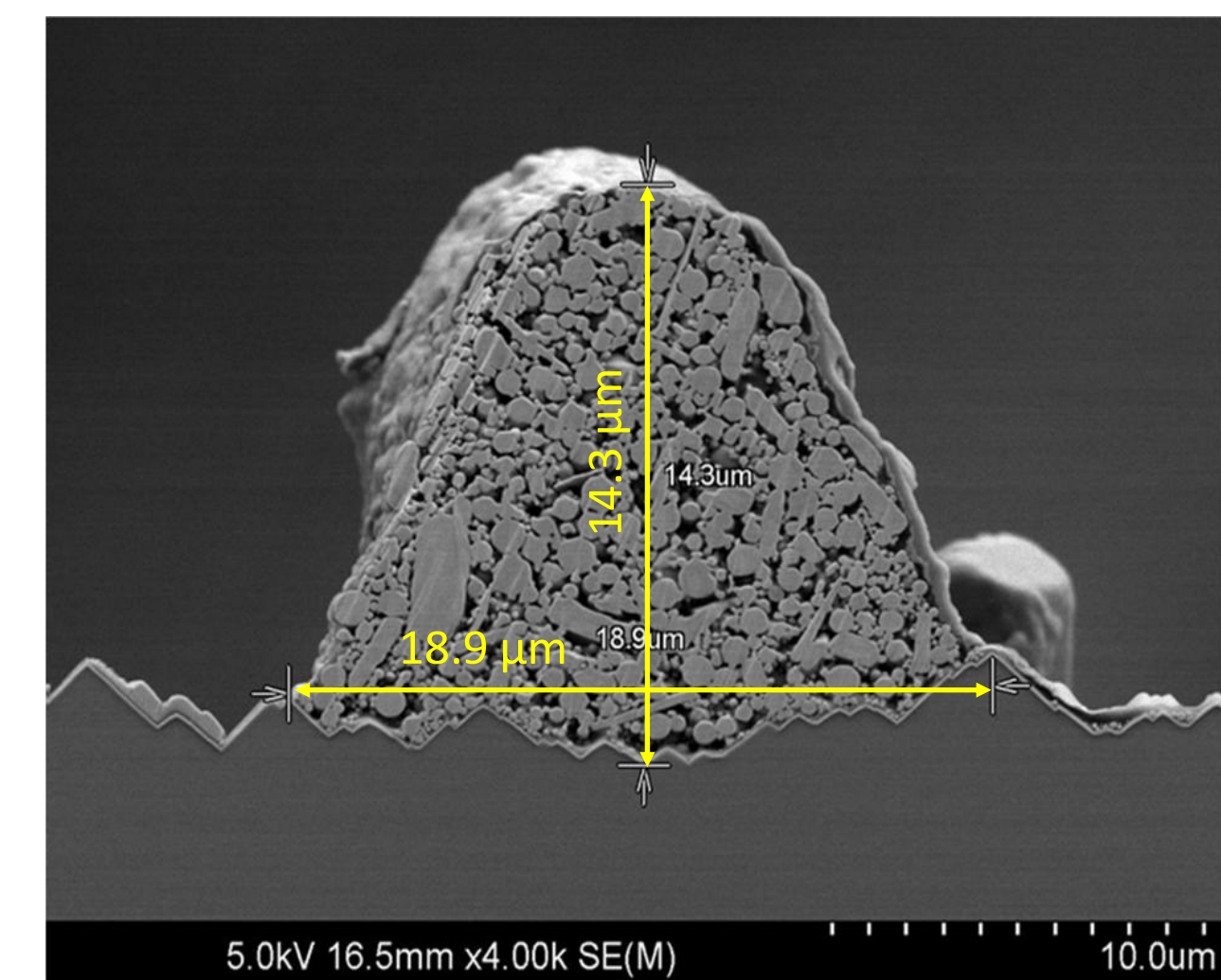


Copprint paste evolution



0 gen	LF-350	2020	5-6 $\mu\Omega\text{cm}$	55 μm spreading
1st gen	LF-371	2021	5 $\mu\Omega\text{cm}$	30 μm spreading
2nd gen	LF-380	2022	7 $\mu\Omega\text{cm}$	20 μm spreading
3rd gen	LF-365	2024	5-6 $\mu\Omega\text{cm}$	9-12 μm spreading
4th gen	LF-366	2025	5 $\mu\Omega\text{cm}$	5-6 μm spreading

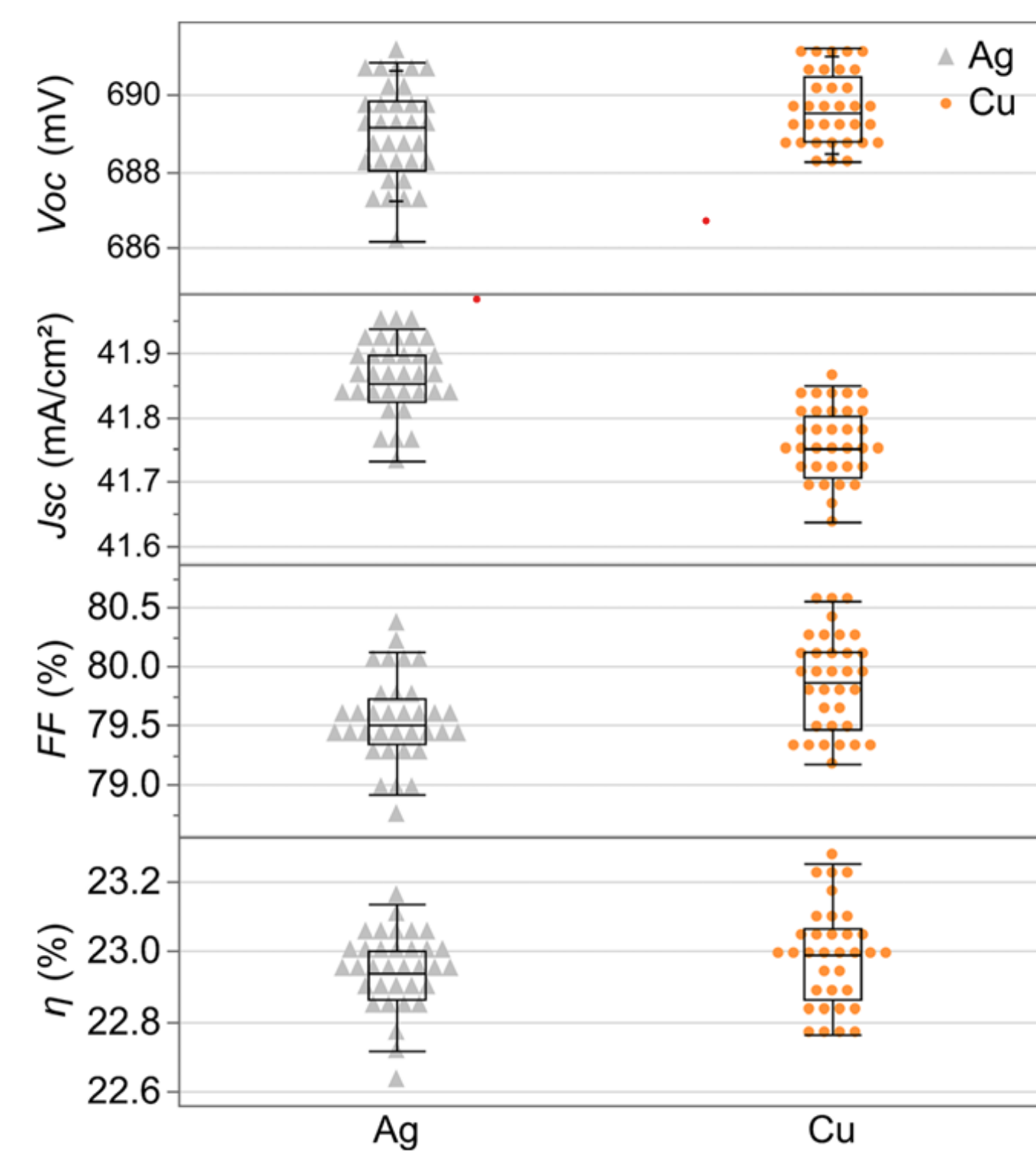
LF-366 cross-section



Screen parameter: finger opening width: 20 μm .

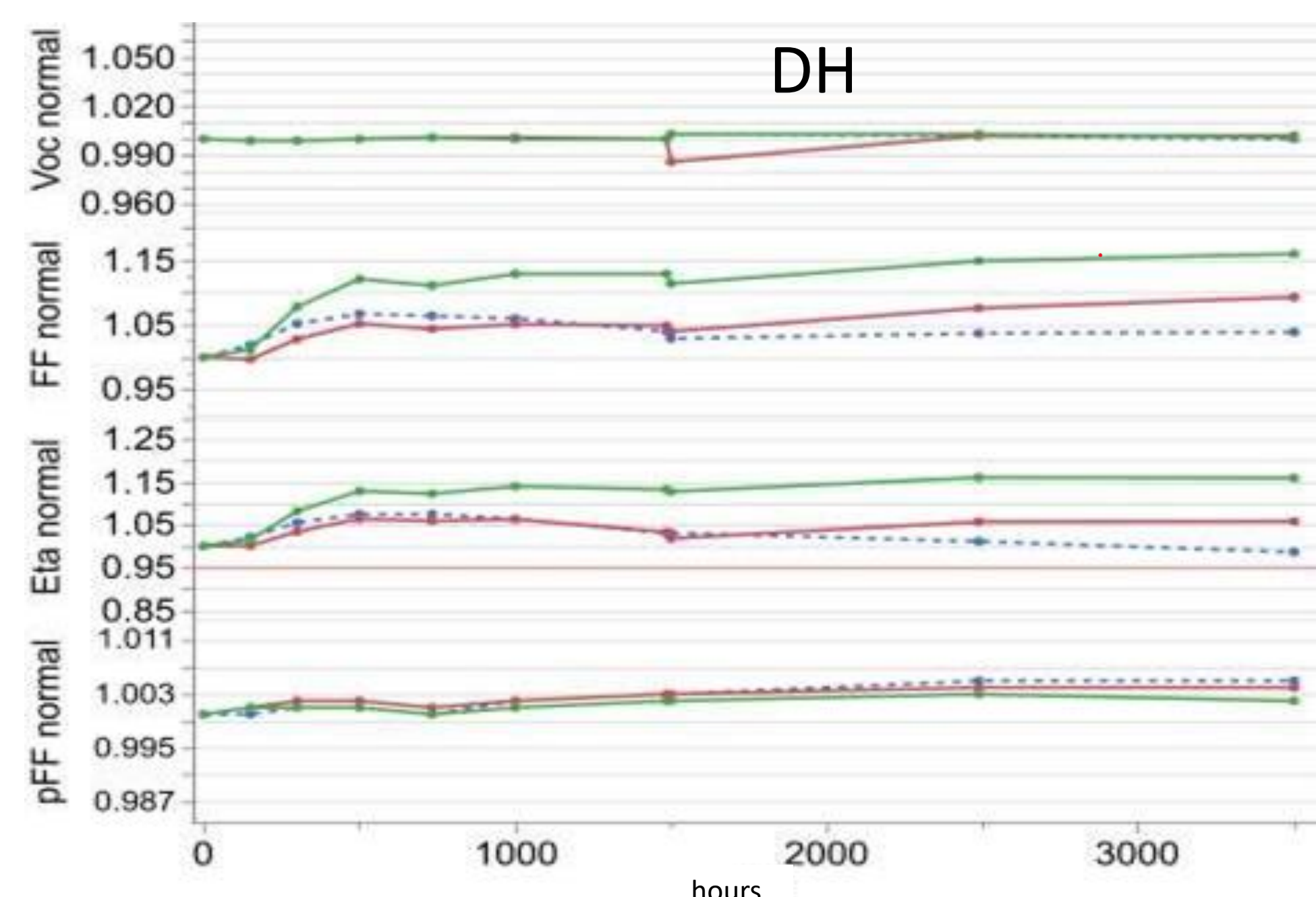
Printing performance and aspect ratios are comparable to standard silver and silver-coated copper pastes.

ISC Konstanz IBC Zebra cells with Cu Busbars and fingers

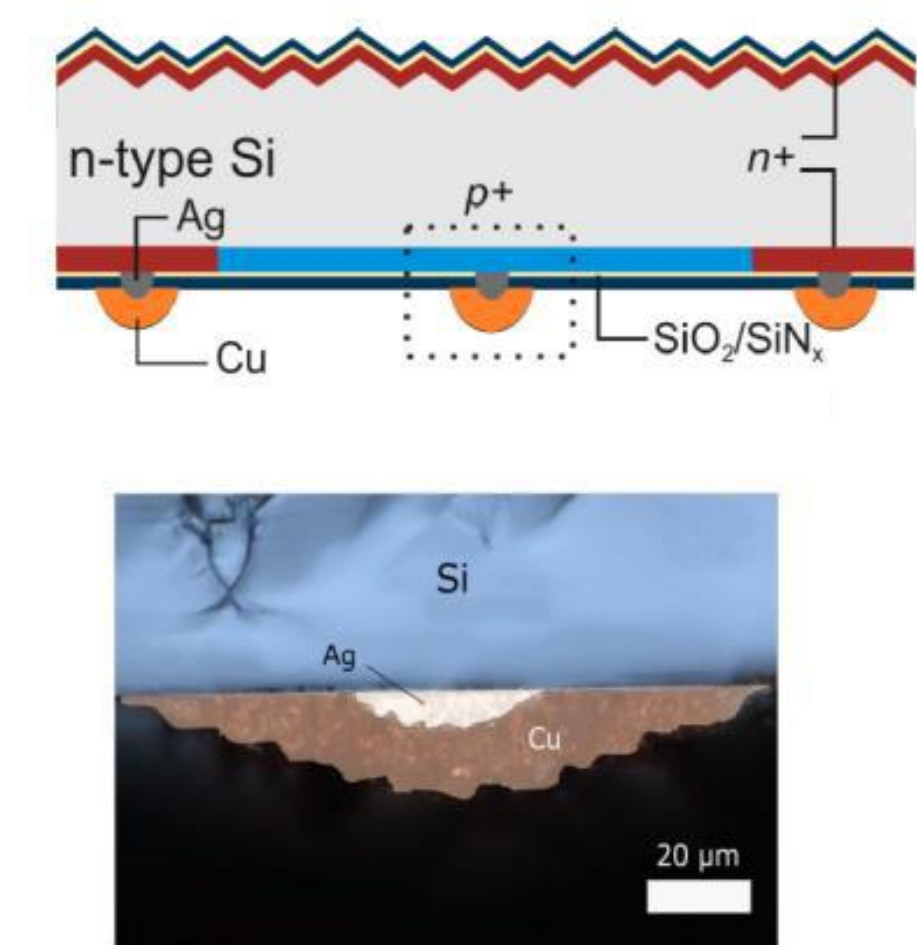


Same efficiency was achieved for both the Cu metallized group and the reference Ag metallized group with average efficiency of 23%.

Chen, Ning, et al. "Thermal Stable High-Efficiency Copper Screen Printed Back Contact Solar Cells." Solar RRL 7.2 (2023):2200874

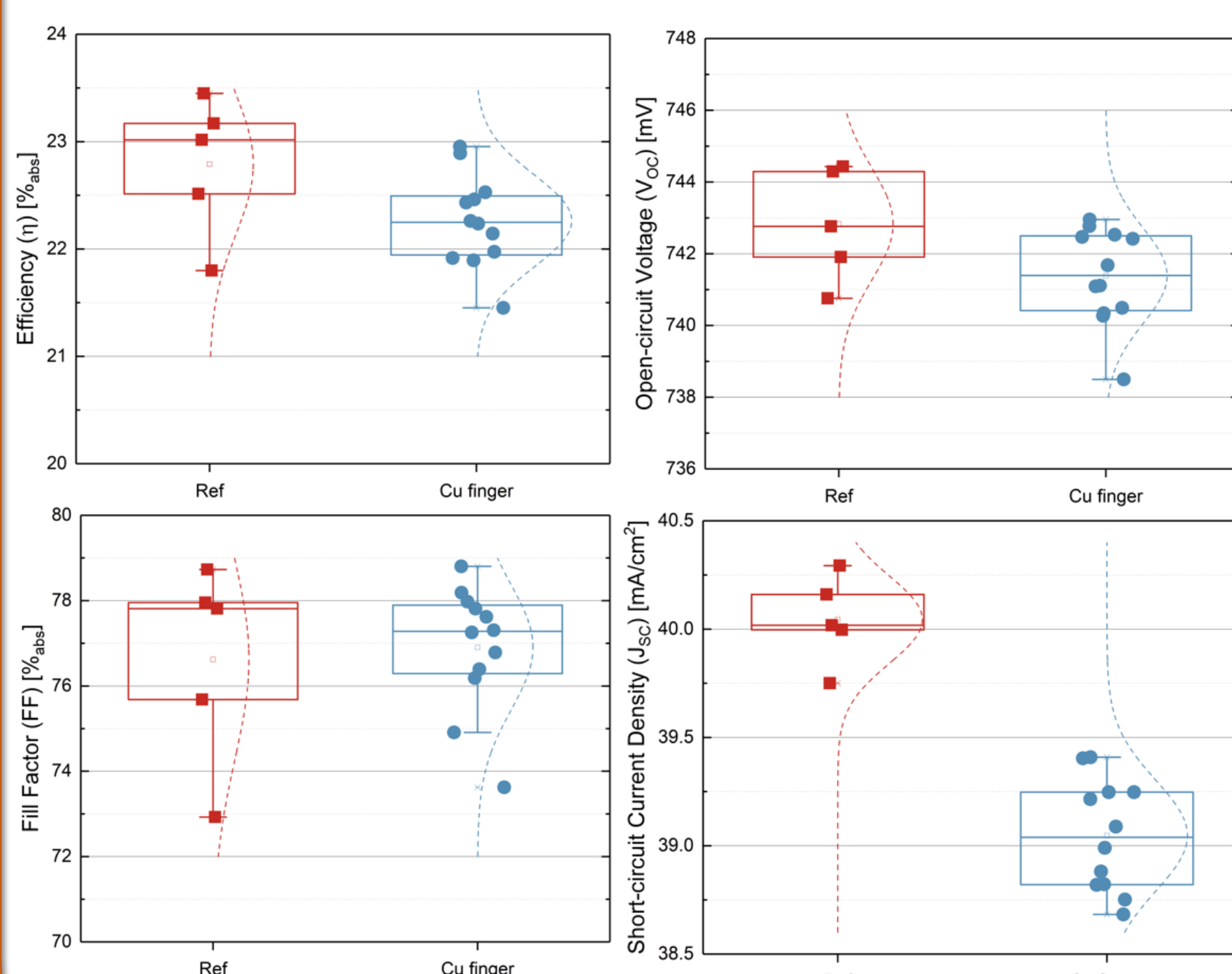


The solar cells are stable and no Cu in-diffusion is observed under damp heat (85 °C, 85% relative humidity).

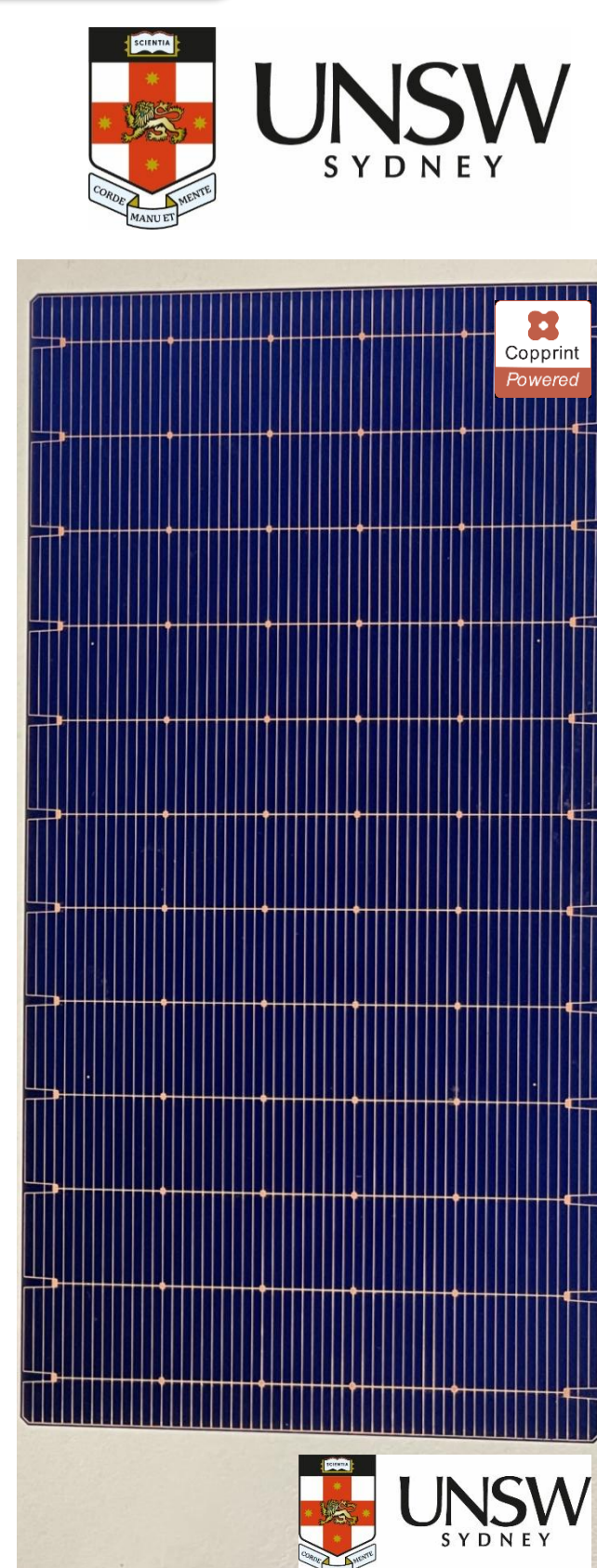


Cu finger on Ag contacts

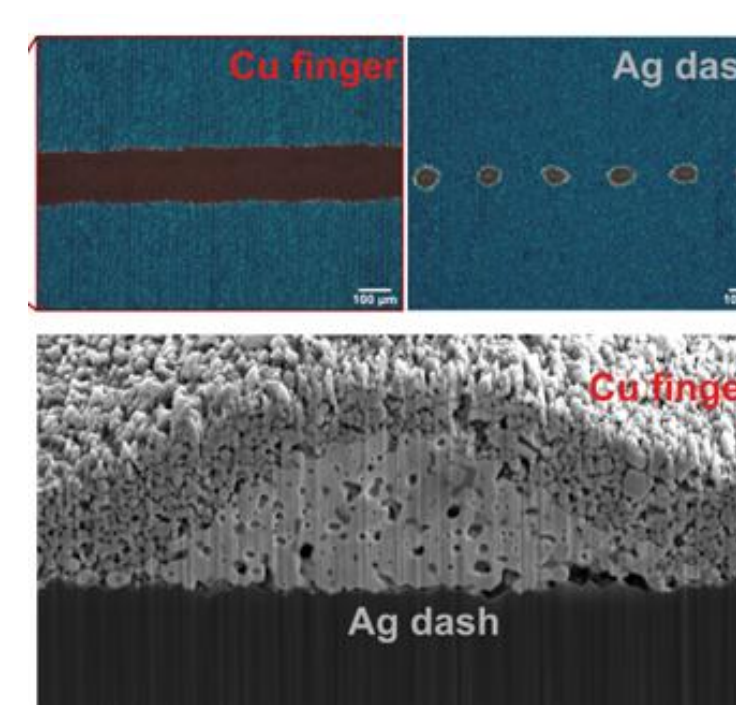
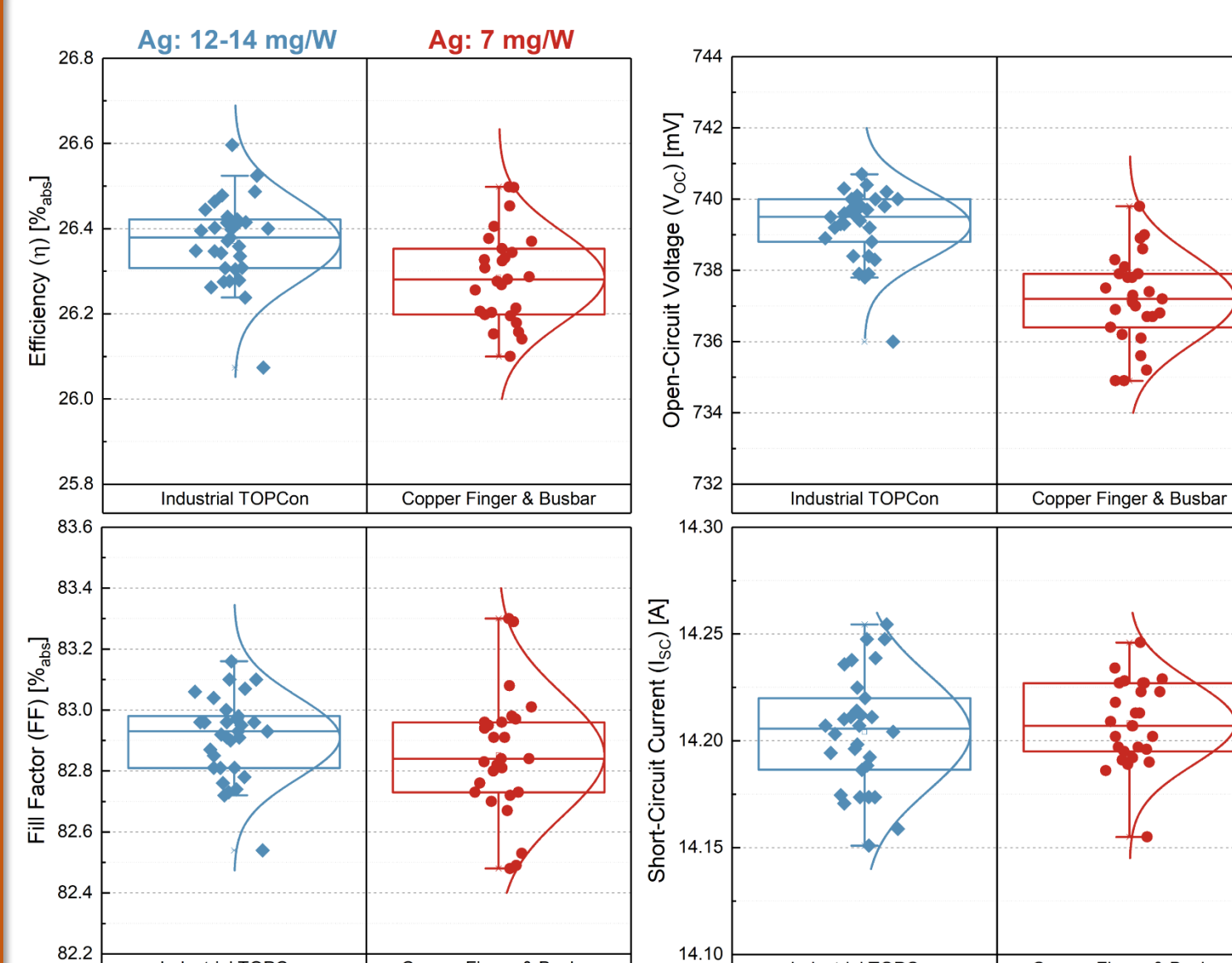
UNSW HJT cells results



An equal or up to 0.5% drop in efficiency for Cu-HJT cells is demonstrated.

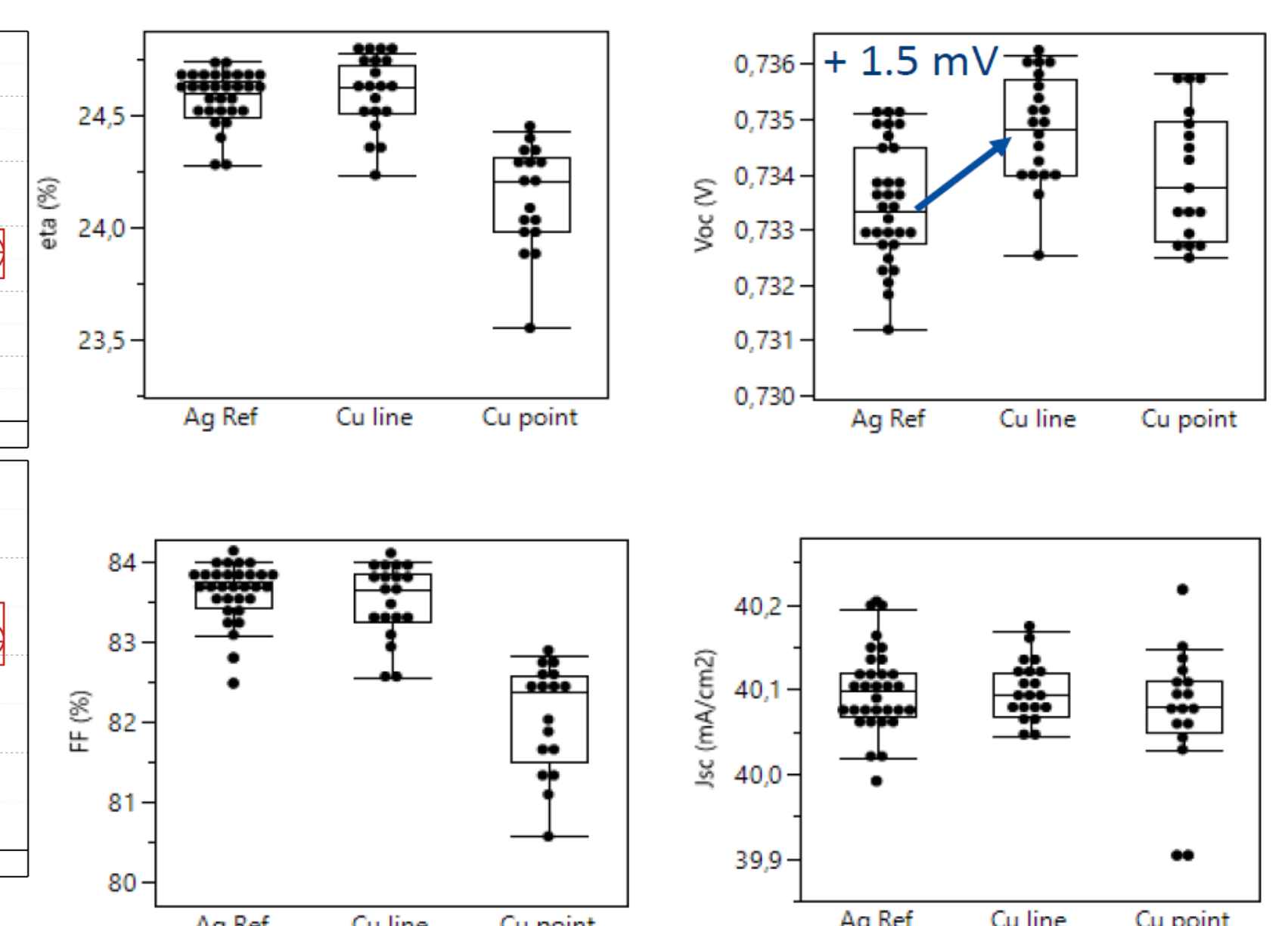


TOPCon



Zhang et al. "Ultra-Lean Silver Screen-Printing for Sustainable Terawatt-Scale Photovoltaic." Solar RRL 8.17 (2024):2400478

ISC Konstanz



An equal or up to 0.2% drop in efficiency for Cu-TOPCon cells.

Soldering on Cu-BB with high peel force is possible.

Lossen et al., "Screen Printed Cu-TOPCon Cells With Reduced Ag Consumption.", EUPVSEC 2025



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